IC Packaging Markets

2013 Global Report Series

With annual shipment around 200 billion units, the complex IC packaging market requires extensive analysis. To provide this analysis **New Venture Research (NVR)** offers four reports for covering the IC packaging market.

The first report, **The Worldwide IC Packaging Market - 2013 Edition**, presents NVR's annual forecast for each of the major package families by semiconductor device type (2011-2017). This report also presents NVR's continuing, extensive coverage of the OSAT market.

The second report, **IC Package Pitch, Leadframe Plating, and Substrate Markets - 2013 Edition**, forecasts the pitch for all major IC package families by I/O count ranges, as well as forecasts of plating options for the leadframes. Lead-free issues also discussed. Substrate forecasts also included. Forecasts are for years 2012 - 2017.

The third report, ***The Array IC Packaging Market* - 2013 Edition,** analyzes the market for BGAs/LGAs, FBGAs/FLGAs, and WLP packages including Fan-Out WLP, plus Fan-In or Multi-Row QFN. Forecasts are for years 2012 - 2017.

The fourth report, **The Multi-Component IC Packaging Market - 2013 Edition,** analyzes stacked packages, SiPs, and through-via technologies over the next five years. Forecasts are for years 2011 - 2017.

These IC packaging reports provide the most comprehensive analysis available today on the IC packaging markets (more details are provided on the next page).

Order Form

Payment Method

Check in the amount of $ ________________ is enclosed.

Invoice per P.O. # ______________________

Please charge: Visa MasterCard American Express

Card # ______________________________ Exp.________

Name On Card______________________________

Signature__________________________ Date_____________

Shipping Address

Name ______________________________

Title ______________________________

Company ______________________________

Address ______________________________

City/State/Zip ______________________________

Telephone ______________________________

Fax ______________________________

E-mail ______________________________

REPORT TITLE	PRICE	QTY	TOTAL
Report 1: The Worldwide IC Packaging Market - 2013 Edition	$3,495		
Report 2: IC Package Pitch, Leadframe Plating, and Substrate Markets- 2013 Edition	$ 995		
Report 3: The Array IC Packaging Market- 2013 Edition	$ 995		
Report 4: The Multi-Component IC Packaging Market - 2013 Edition	$1,495		
Total (PDF Only)	**$6,980**		
Discount for all four reports	$2,000		
The Complete Annual IC Packaging Series with discount	**$4,980**		
Add Excel Spreadsheet of all tables for The Worldwide IC Packaging report - $750			
		Subtotal	
		TOTAL	

Returns: No return privileges. **International Orders:** Must be prepaid, please contact us for payment arrangements.

New Venture Research
337 Clay St., Suite 101
Nevada City, CA 95959
Tel: (408) 244-1100 Fax: (530) 265-1998
www.newventureresearch.com; kwilliams@newventureresearch.com

Report 1: The Worldwide IC Packaging Market - 2013 Edition

Chapter 1: Introduction
Chapter 2: Executive Summary
Chapter 3: The Economic State of the Industry
Chapter 4: IC Package Forecast by Device Type
Chapter 5: IC Package Forecast by Package Family
Chapter 6: Packaging Contractor Market
Chapter 7: OSAT Profiles

Publish date, May 2013 - 425 pages

Report 2: IC Package Pitch, Leadframe Plating, and Substrate Markets - 2013 Edition

Chapter 1: Introduction
Chapter 2: Executive Summary
Chapter 3: The Economic State of the Industry
Chapter 4: Pitch by Major Package Family and I/O Count Range
Chapter 5: Leadframe Plating Options and Lead-free Issues
Chapter 6: Substrates

Publish date, August 2013 - 200 pages

Report 3: The Array IC Packaging Market - 2013 Edition

Chapter 1: Introduction
Chapter 2: Executive Summary
Chapter 3: The Economic State of the Industry
Chapter 4: BGA/LGA By I/O Count and Device Type
Chapter 5: FBGA / FLGA By I/O Count and Device Type
Chapter 6: WLP–Including Fan-Out
Chapter 7: QFN–Including Fan-In or Multi-Row

Publish date, October 2013 - 110 pages

Report 4: The Multi-Component IC Packaging Market - 2013 Edition

Chapter 1: Introduction
Chapter 2: Executive Summary
Chapter 3: The Economic State of the Industry
Chapter 4: Stacked Packages
Chapter 5: SiPs
Chapter 6: Through-Via Technology

Publish date, December 2013 - 175 pages

About the Author

Sandra L Winkler has been an industry analyst since 1988, and has authored many off-the-shelf as well as custom market research reports. Ms. Winkler began her analyst career in the telecommunications industry, with **Frost and Sullivan** but evolved to the semiconductor packaging industry as of 1995. She is the author of more than 30 reports for **NVR** on this and other topics, including ***The Worldwide IC Packaging Market, Advanced IC Packaging Markets and Trends***, and ***IC Packaging Materials***. She is widely published in ***Chip Scale Review, Global SMT & Packaging News***, and contributes to the **IEEE/CPMT** newsletter and other print media. Ms. Winkler holds an MBA from Santa Clara University and is on the executive planning committee of the **IEEE/CPMT**, Santa Clara Valley chapter.